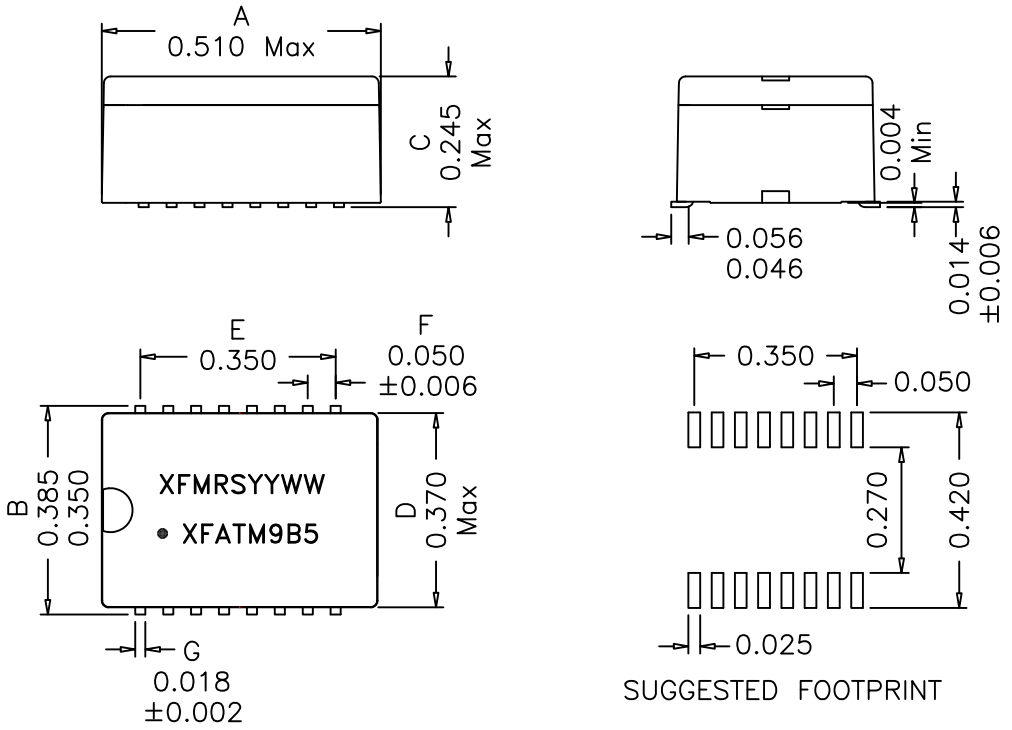
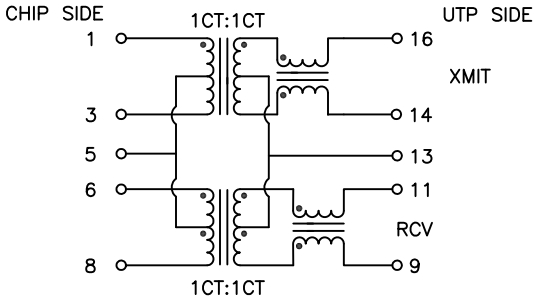
1. Mechanical Dimensions:



2. Schematic:



3. Electrical Specifications: @25°C

UTP Impedance: 100 OHMS
Turns Ratio: TX : 1CT:1CT ±2% RX : 1CT:1CT ±2%
Isolation Voltage: 1500 VAC (Input to Output)
UTP Side OCL: 350uH Minimum @100KHz,100mV 8mADC
CHIP SIDE Q: 5 Min @10KHz 50mV
Rise Time (10–90%): 4.0ns Typical
Insertion Loss (1–100MHz): –1.0dB Maximum
Return Loss : 30MHz 60MHz 80MHz
–20dB –14dB –11.5dB (Typical)
CMRR (1MHz–100MHz): –40dB TYPICAL
Crosstalk Attenuation: –40dB Minimum

Notes:

1. Solderability: Leads shall meet MIL–STD–202G, Method 208H for solderability.
2. Flammability: UL94V–0
3. ASTM oxygen index: > 28%
4. Insulation System: Class F 155°C. UL file E151556
5. Operating Temperature Range: All listed parameters are to be within tolerance from –40°C to +85°C
6. Storage Temperature Range: –55°C to +125°C
7. Aqueous wash compatible
8. SMD Lead Coplanarity: ±0.004"(0.102mm)
9. Electrical and mechanical specifications 100% tested
10. RoHS Compliant Component

DOC. REV: B/1

XFMRS INC www.XFMRS.com	Title: 10/100 BASE MAGNETIC MODULE		
UNLESS OTHERWISE SPECIFIED TOLERANCES: .xxx ±0.010 Dimensions in Inch	P/N: XFATM9B5		REV. B
	DWN.	Yuan	Nov–30–12
	CHK.	YK Liao	Nov–30–12
SHEET 1 OF 1	APP.	BSJ	Nov–30–12